

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	56	semiconductor adj substrate and microstrip and inductor and conductive adj pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:16
L3	192612	2 and carrieradj layer and foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:18
L4	1	2 and carrier adj layer and foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:18
L7	2	semiconductor adj substrate and microstrip and inductor and conductive adj pattern and isolating and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:26
L8	3473	361/772-779.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:47
L9	149	8 and inductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:48
L10	220	9 and substrate and pattern coile and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:48
L12	38	9 and substrate and pattern and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:49

L18	56	semiconductor adj substrate and microstrip and inductor and conductive adj pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:54
L22	50	semiconductor adj substrate and microstrip and inductor and conductive adj pattern and inductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:55
L30	3107	substrate and pattern and pads and patterned adj layer and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 11:58
L33	1045	substrate and pattern and electronic adj device and electrode and inductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 12:01
L34	21	30 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 12:01
L35	21	34 and patterned adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 12:02
L36	1	34 and patterned adj layer and electroconductive adj patterned	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 12:02
L41	623	361/772.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:38

L42	521	361/773.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:38
L43	742	361/774.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:38
L44	285	361/775.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:38
L45	415	361/776.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:39
L46	950	361/777.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:39
L47	250	361/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:39
L48	532	361/779.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:39
L49	16	41 and 42 and 43 and 43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 13:39
L50	1	("2002/0131255").URPN.	USPAT	OR	ON	2008/03/28 13:44

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